

LVDS Interface ICs

35bit LVDS Transmitter 35:5 Serializer



BU8254KVT

●Description

LVDS Interface IC of ROHM "Serializer" "Deserializer" operate from 8MHz to 150MHz wide clock range, and number of bits range is from 35 to 70. Data is transmitted seven times (7X) stream and reduce cable number by 3(1/3) or less. The ROHM's LVDS has low swing mode to be able to expect further low EMI.

●Features

- 35bits data of parallel LVCMOS level inputs are converted to five channels of LVDS data stream.
- 30bits of RGB data and 5bits of timing and control data(HSYNC, VSYNC, DE, CNTL1, CNTL2) are transmitted up to 784Mbps effective rate per LVDS channel.
- Support clock frequency from 8MHz up to 112MHz.
- Support consumer video format including 480i, 480P, 720P and 1080i as well.
- Clock edge selectable
- Power down mode
- Support spread spectrum clock generator.
- Support reduced swing LVDS for low EMI.
- 30bit LVDS receiver is recommended to use BU8255KVT.

●Applications

Flat Panel Display

●Precaution

- This chip is not designed to protect from radioactivity.
- The chip is made strictly for the specific application or equipment.
Then it is necessary that the unit is measured as need.
- This document may be used as strategic technical data which subjects to COCOM regulations.

Status of this document

The Japanese version of this document is the official specification.

Please use the translation version of this document as a reference to expedite understanding of the official version.

If there is any uncertainty in translation version of this document, official version takes priority.

Jun.2008

●Block Diagram

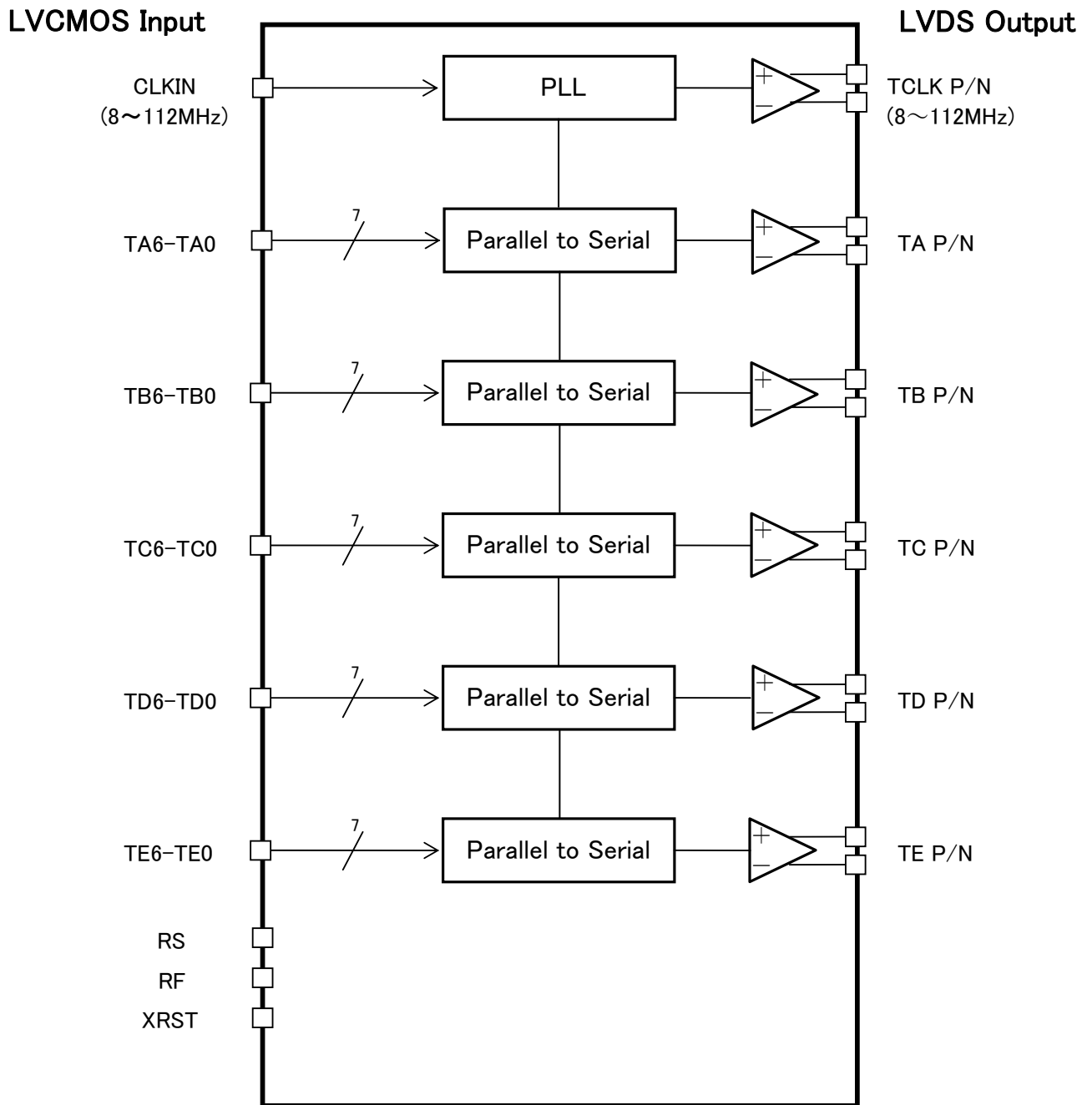
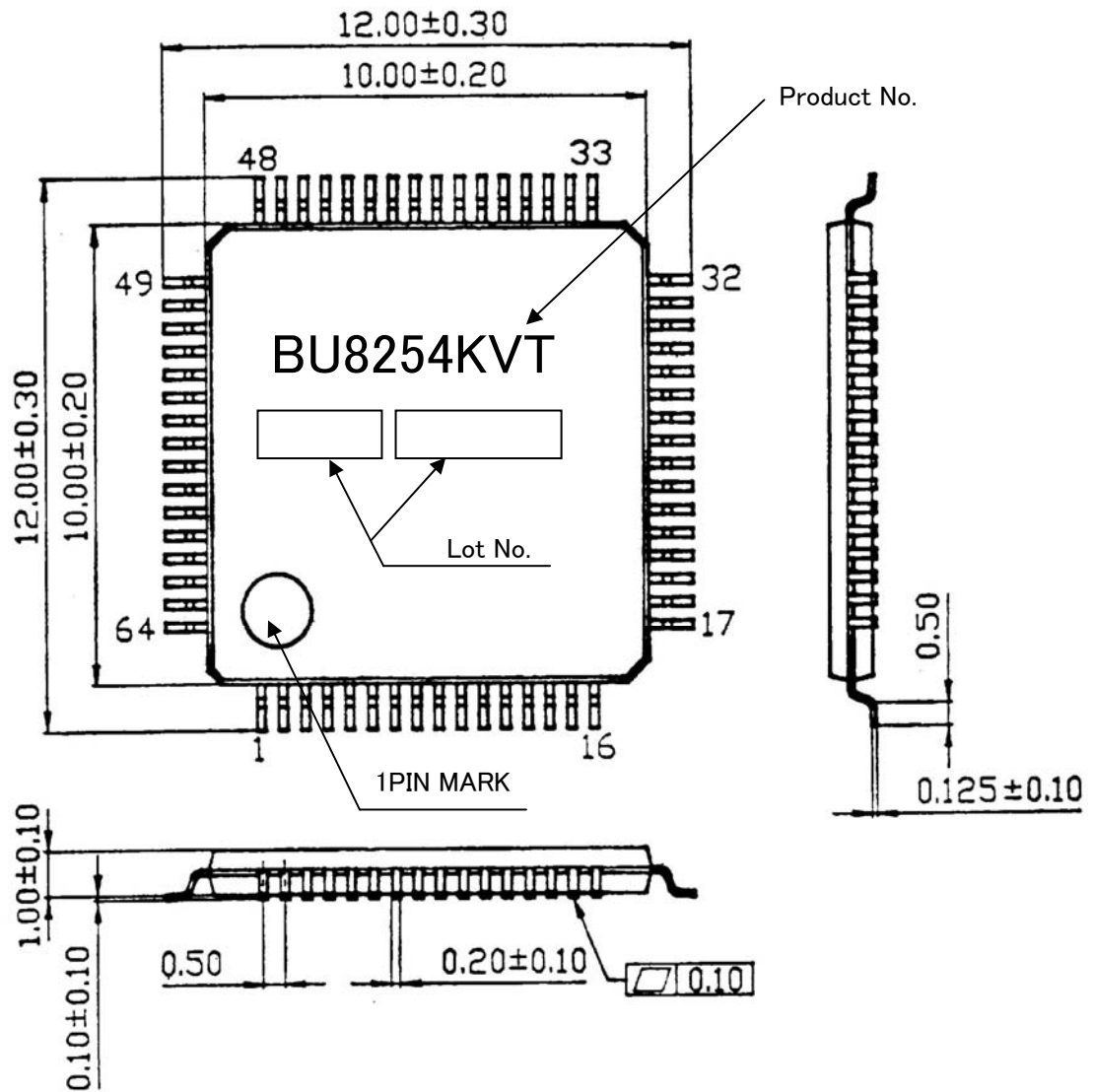


Figure-1 Block Diagram

●TQFP64V Package Outline and Specification



(UNIT: mm)

Figure-2 TQFP64V Package Outline and Specification

● Pin configuration

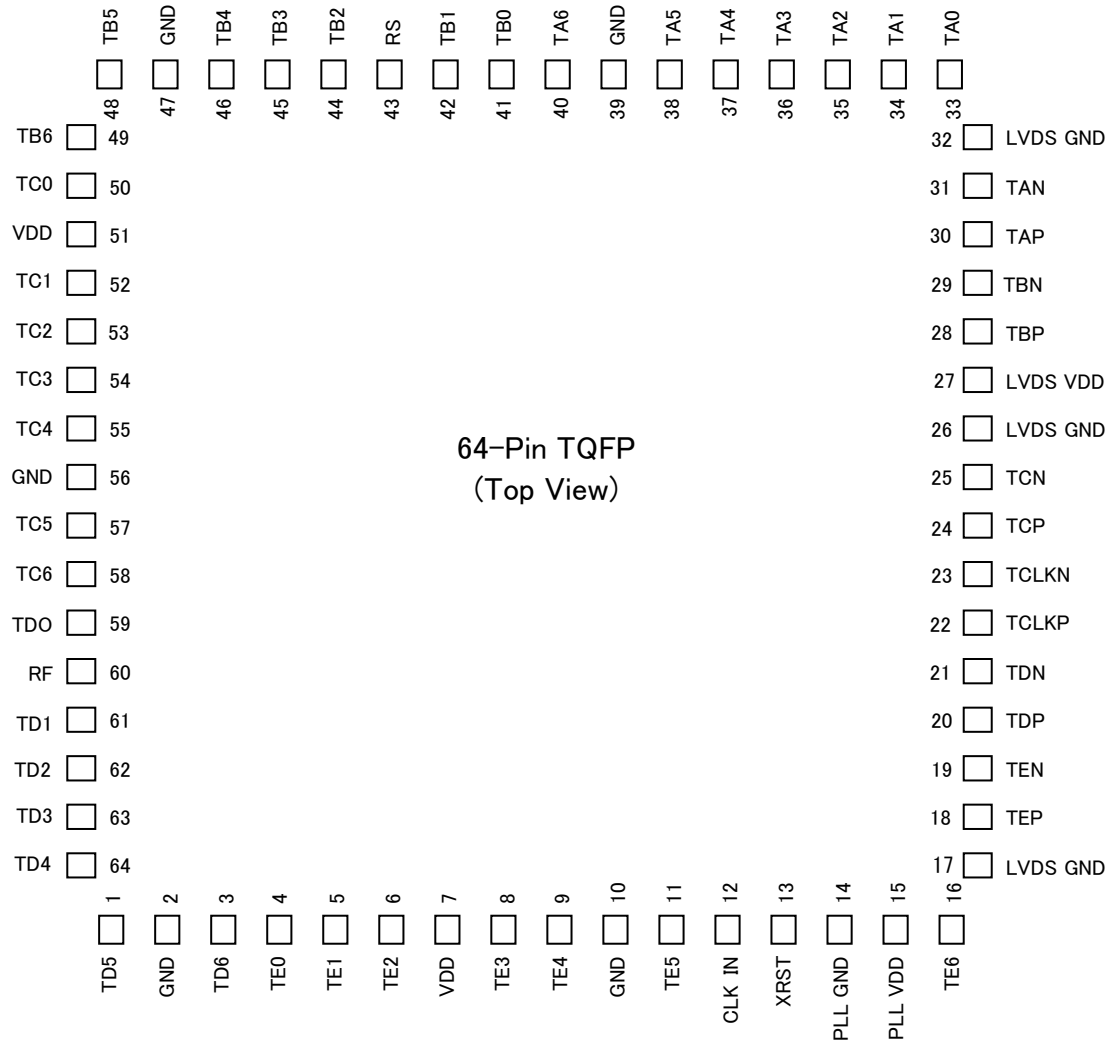


Figure-3 Pin Diagram (Top View)

● Pin Description

Table 1 : Pin Description

Pin Name	Pin No.	Type	Descriptions												
TAP, TAN	30,31	LVDS OUT	LVDS data out.												
TBP, TBN	28,29	LVDS OUT													
TCP, TCN	24,25	LVDS OUT													
TDP, TDN	20,21	LVDS OUT													
TEP, TEN	18,19	LVDS OUT													
TCLKP, TCLKN	22,23	LVDS OUT	LVDS clock out.												
TA0~TA6	33,34,35,36,37,38,40	IN	Pixel data inputs.												
TB0~TB6	41,42,44,45,46,48,49	IN													
TC0~TC6	50,52,53,54,55,57,58	IN													
TD0~TD6	59,61,62,63,64,1,3	IN													
TE0~TE6	4,5,6,8,9,11,16	IN													
XRST	13	IN	H : Normal operation, L : Power down (all outputs are Hi-Z)												
RS	43	IN	LVDS swing mode, V_{REF} *1 select. <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>RS</th> <th>LVDS Swing</th> <th>Small Swing Input Support</th> </tr> </thead> <tbody> <tr> <td>V_{DD}</td> <td>350mV</td> <td>N/A</td> </tr> <tr> <td>0.6~1.4V</td> <td>350mV</td> <td>$RS-V_{REF}$</td> </tr> <tr> <td>GND</td> <td>200mV</td> <td>N/A</td> </tr> </tbody> </table> <p>*1 V_{REF} is Input Reference Voltage.</p>	RS	LVDS Swing	Small Swing Input Support	V_{DD}	350mV	N/A	0.6~1.4V	350mV	$RS-V_{REF}$	GND	200mV	N/A
RS	LVDS Swing	Small Swing Input Support													
V_{DD}	350mV	N/A													
0.6~1.4V	350mV	$RS-V_{REF}$													
GND	200mV	N/A													
RF	60	IN	Input clock triggering edge select. H : Rising edge, L : Falling edge.												
VDD	51,7	Power	Power supply pins for LVCMOS inputs and digital core.												
CLKIN	12	IN	Clock input.												
GND	2,10,39,47,56	Ground	Ground pins for LVCMOS inputs and digital core.												
LVDS VDD	27	Power	Power supply pins for LVDS outputs.												
LVDS GND	17,26,32	Ground	Ground pins for LVDS outputs.												
PLL VDD	15	Power	Power supply pin for PLL core.												
PLL GND	14	Ground	Ground pins for PLL core.												

● Electrical characteristics

■ Rating

Table 2 : Absolute Maximum Rating

Parameter	Symbol	Rating		Units
		Min	Max	
Supply Voltage	V_{DD}	-0.3	4.0	V
Input Voltage	V_{IN}	-0.3	$V_{DD}+0.3$	V
Output Voltage	V_{OUT}	-0.3	$V_{DD}+0.3$	V
Storage Temperature Range	T_{stg}	-55	125	°C

Table 3 : Package Power

PACKAGE	Power Dissipation (mW)	De-rating (mW/°C)*1
TQFP64V	700	7.0
	1000*2	10.0*2

*1:At temperature $T_a > 25^{\circ}\text{C}$

*2:Package power when mounting on the PCB board.

The size of PCB board : $70 \times 70 \times 1.6 (\text{mm}^3)$

The material of PCB board :The FR4 glass epoxy board.(3% or less copper foil area)

(It is recommended to apply the above package power requirement to PCB board when the small swing input mode is used)

Table 4 : Recommended Operating Conditions

Parameter	Symbol	Rating			Units	Conditions
		Min	Typ	Max		
Supply Voltage	V_{DD}	3.0	3.3	3.6	V	VDD,LVDSVDD,PLLVD
Operating Temperature Range	T_{opr}	-20	-	85	°C	Clock frequency from 8MHz up to 90MHz
		0	-	70	°C	Cock frequency from 90MHz up to 112MHz

■ DC characteristics

Table 5 : LVCMOS DC Specifications ($V_{DD}=3.0V\sim 3.6V$, $T_a=-20^{\circ}C\sim 85^{\circ}C$)

Symbol	Parameter	Rating			Units	Conditions
		Min	Typ	Max		
V_{IH}	High Level Input Voltage	$V_{DD} \times 0.8$	–	V_{DD}	V	exclude RS pin
V_{IL}	Low Level Input Voltage	GND	–	$V_{DD} \times 0.2$	V	
V_{IHRS}	High Level Input Voltage	$V_{DD} \times 0.8$	–	V_{DD}		RS pin
V_{ILRS}	Low Level Input Voltage	GND	–	0.2		
V_{DDQ}^{*1}	Small Swing Voltage	1.2	–	2.8	V	
V_{REF}	Input Reference Voltage	–	$V_{DDQ}/2$	–	–	Small Swing($RS=V_{DDQ}/2$)
V_{SH}^{*2}	Small Swing High Level Input Voltage	$V_{DDQ}/2$ +200mV	–	–	V	$V_{REF}=V_{DDQ}/2$
V_{SL}^{*2}	Small Swing Low Level Input Voltage	–	–	$V_{DDQ}/2$ –200mV	V	$V_{REF}=V_{DDQ}/2$
I_{INC}	Input Current	–	–	± 10	μA	$0V \leq V_{IN} \leq V_{DD}$

*1: V_{DDQ} voltage defines max voltage of small swing input. It is not an actual input voltage.

*2: Small swing signal is applied to TA[6:0], TB[6:0], TC[6:0], TD[6:0], TE[6:0], CLKIN.

Table 6 : LVDS Transmitter DC Specifications ($V_{DD}=3.0V\sim 3.6V$, $T_a=-20^{\circ}C\sim 85^{\circ}C$)

Symbol	Parameter	Rating			Units	Conditions	
		Min	Typ	Max			
V_{OD}	Differential Output Voltage	250	350	450	mV	RL=100Ω	Normal swing RS= V_{DD}
		100	200	300	mV		Reduced swing RS=GND
ΔV_{OD}	Change in VOD between complementary output states	–	–	35	mV	RL=100Ω	
V_{OC}	Common Mode Voltage	1.125	1.25	1.375	V		
ΔV_{OC}	Change in VOC between complementary output states	–	–	35	mV		
I_{OS}	Output Short Circuit Current	–	–	–24	mA	$V_{OUT}=0V$, RL=100Ω	
I_{OZ}	Output TRI-STATE Current	–	–	± 10	μA	XRST=0V, $V_{OUT}=0V$ to V_{DD}	

■ Supply Current

Table 7 : Supply Current

Symbol	Parameter	Rating		Units	Conditions	
		Typ	Max			
I _{TCCG}	Transmitter Supply Current	57	-	mA	RL=100Ω,CL=5pF V _{DD} =3.3V,RS=V _{DD} Gray Scale Pattern	f=85MHz
		42	-	mA	RL=100Ω,CL=5pF V _{DD} =3.3V,RS=GND Gray Scale Pattern	f=85MHz
I _{TCCW}	Transmitter Supply Current	62	-	mA	RL=100Ω,CL=5pF V _{DD} =3.3V,RS=V _{DD} Worst Case pattern	f=85MHz
		45	-	mA	RL=100Ω,CL=5pF V _{DD} =3.3V,RS=GND Worst Case pattern	f=85MHz
I _{TCCS}	Transmitter Power Down Supply Current	-	10	μA	XRST=L	

Gray Scale Pattern

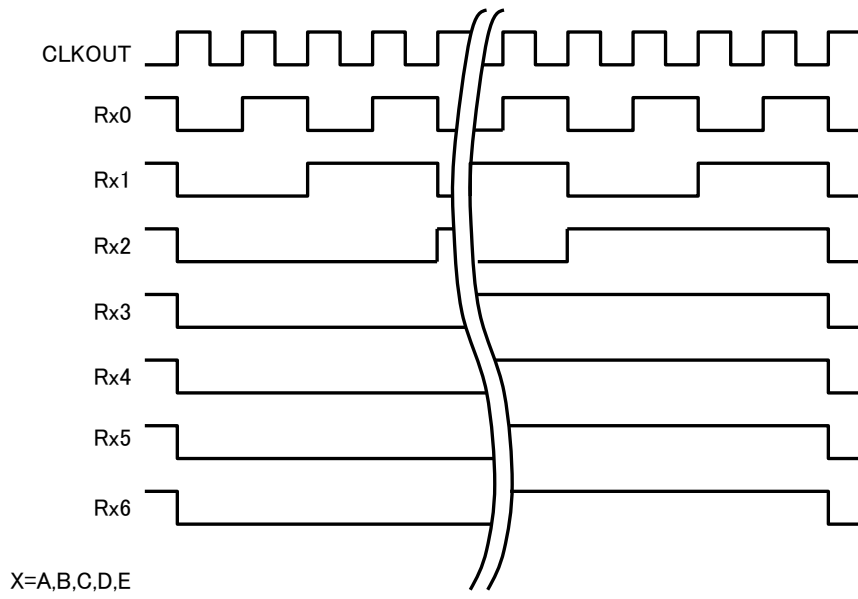


Figure-4 Gray scale pattern

Worst Case Pattern (Maximum Power condition)

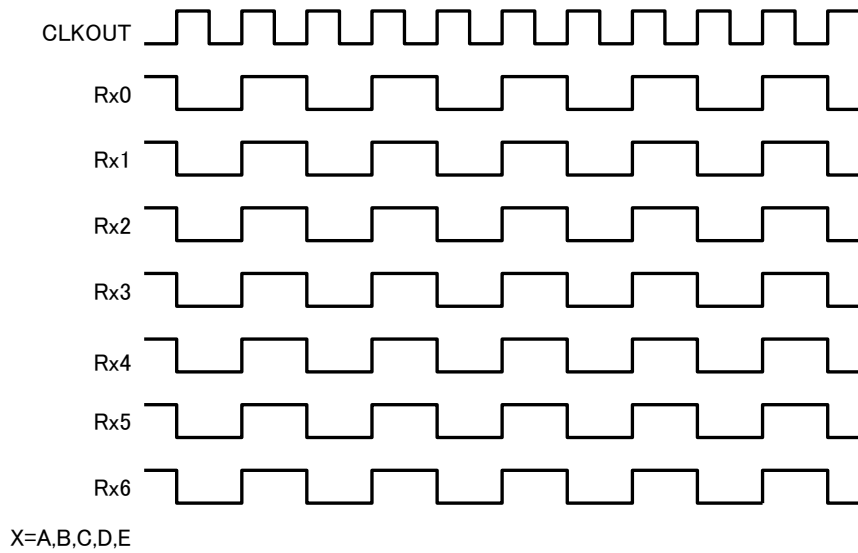


Figure-5 Worst Case Pattern

■ AC characteristics

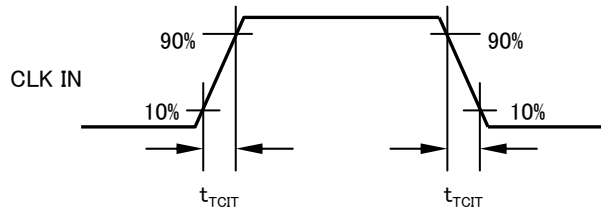
Table 8 : Switching Characteristics

Symbol	Parameter	Min	Typ	Max	Units
t_{TCIT}	CLK IN Transition time	–	–	5.0	ns
t_{TCP}	CLK IN Period	8.93	–	125.0	ns
t_{TCH}	CLK IN High Time	$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
t_{TCL}	CLK IN Low Time	$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
t_{TCD}	CLK IN to TCLK+/-Delay	–	t_{TCP}	–	ns
t_{TS}	LVSMOS Data Set up to CLK IN	2.5	–	–	ns
t_{TH}	LVC MOS Data Hold from CLK IN	0	–	–	ns
t_{LVT}	LVDS Transition Time	–	0.6	1.5	ns
t_{TOP1}	Output Data Position 0	–0.2	0.0	+0.2	ns
t_{TOP0}	Output Data Position 1	$\frac{t_{TCP}}{7} - 0.2$	$\frac{t_{TCP}}{7}$	$\frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP6}	Output Data Position 2	$2 \frac{t_{TCP}}{7} - 0.2$	$2 \frac{t_{TCP}}{7}$	$2 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP5}	Output Data Position 3	$3 \frac{t_{TCP}}{7} - 0.2$	$3 \frac{t_{TCP}}{7}$	$3 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP4}	Output Data Position 4	$4 \frac{t_{TCP}}{7} - 0.2$	$4 \frac{t_{TCP}}{7}$	$4 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP3}	Output Data Position 5	$5 \frac{t_{TCP}}{7} - 0.2$	$5 \frac{t_{TCP}}{7}$	$5 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP2}	Output Data Position 6	$6 \frac{t_{TCP}}{7} - 0.2$	$6 \frac{t_{TCP}}{7}$	$6 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TPLL}	Phase Locked Loop Set Time	–	–	10.0	ms

● AC Timing

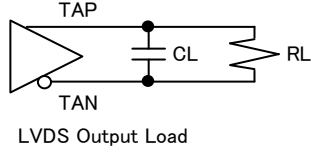
■ AC Timing Diagrams

LVC MOS Input

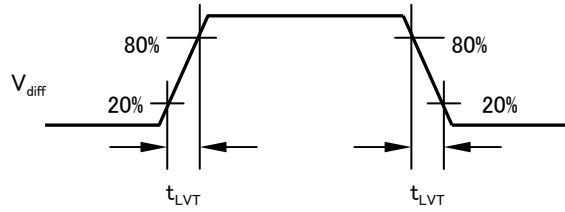


LVDS Output

$$V_{diff} = (TAP) - (TAN)$$



LVDS Output Load



LVC MOS Input

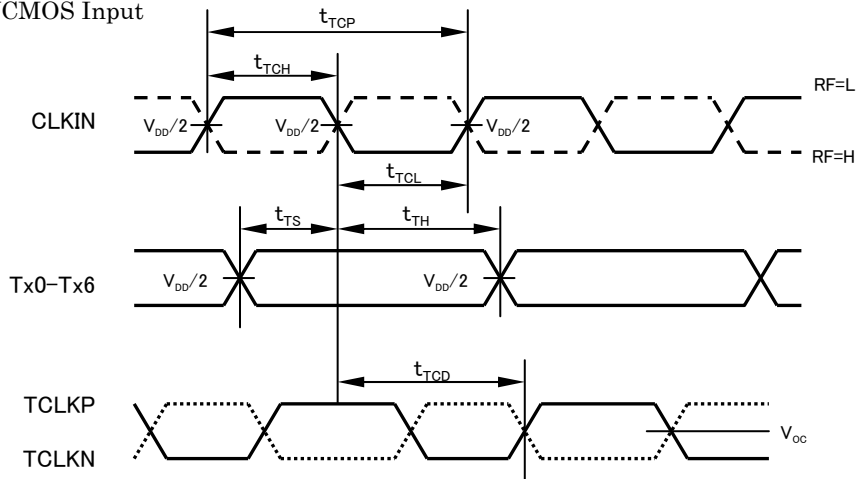


Figure-6 AC Timing Diagrams

■ Small Swing Inputs

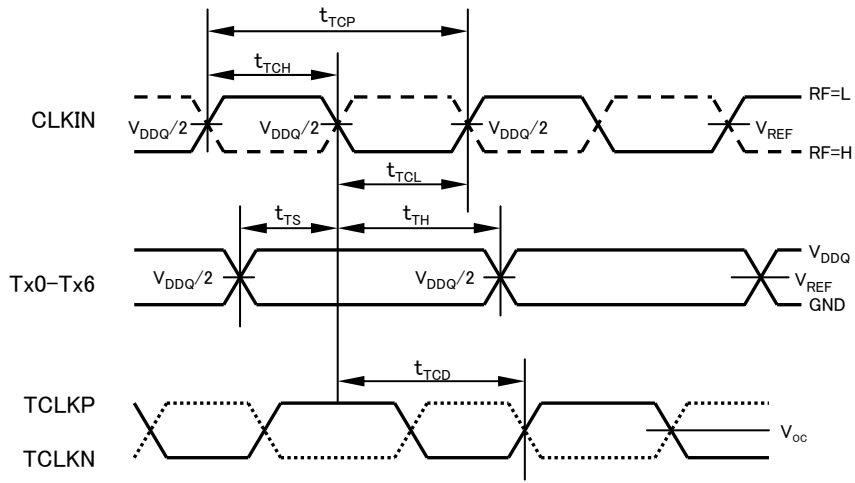


Figure-7 Small Swing Inputs

AC Timing Diagrams

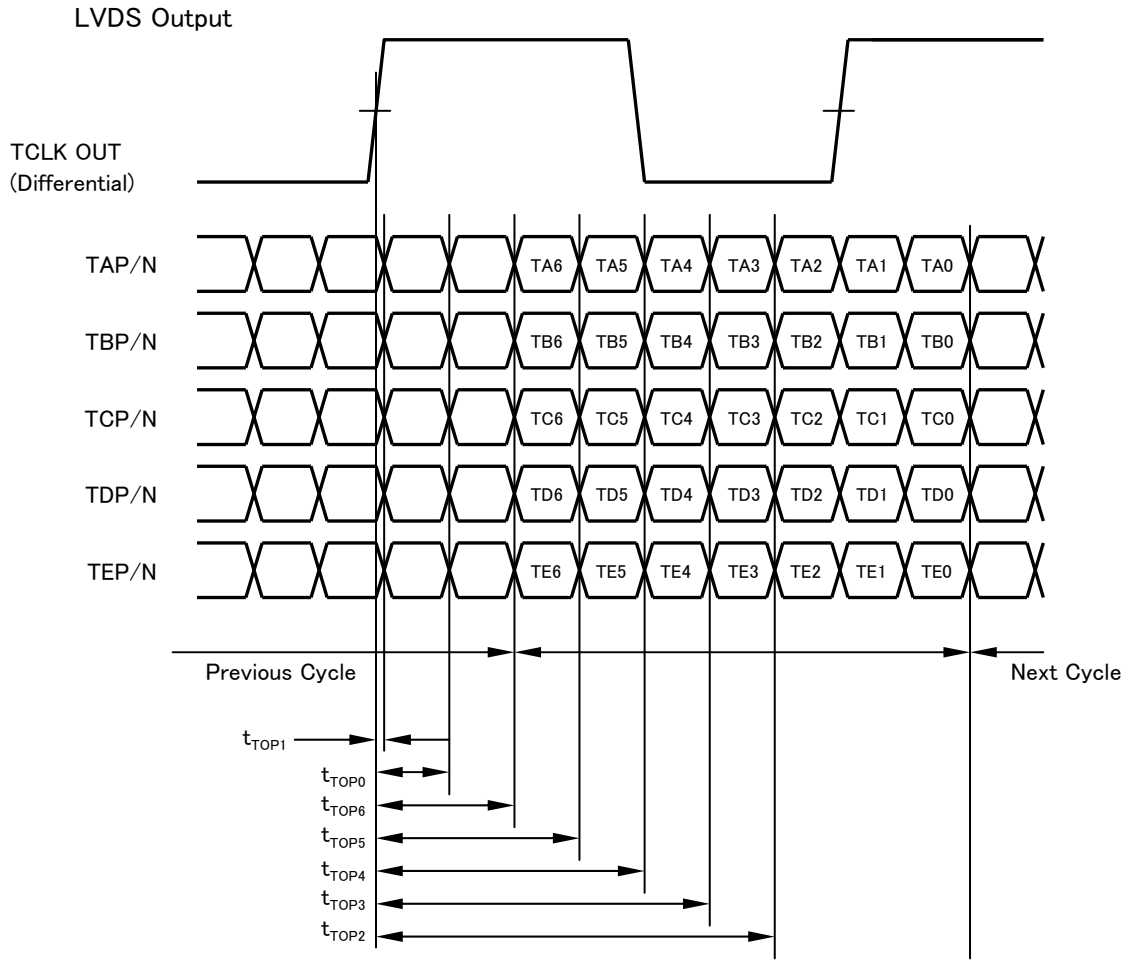


Figure-8 AC Timing Diagrams

Phase Locked Loop Set Time

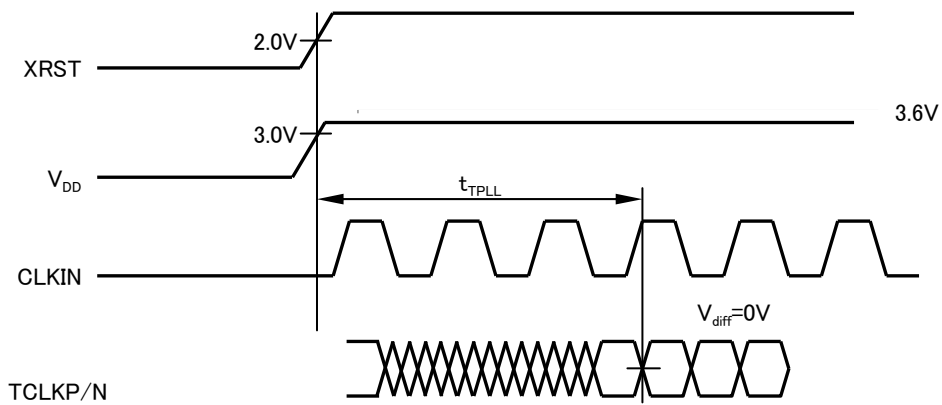


Figure-9 Phase Locked Loop Set Time

●About the Power On Reset

Power On Reset is not mandatory for this device.

(The PD pin should be set to high level when Power On Reset procedure is not used.)

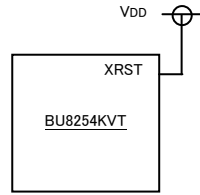


Figure-10 Terminal connection when Power On Reset is not used

However, Power On Reset procedure is strongly recommend for internal logic initialization by following two methods.

- ① The method of using CR circuit.
- ② The method of using external specific IC.

It is recommend to do enough examination for target application.

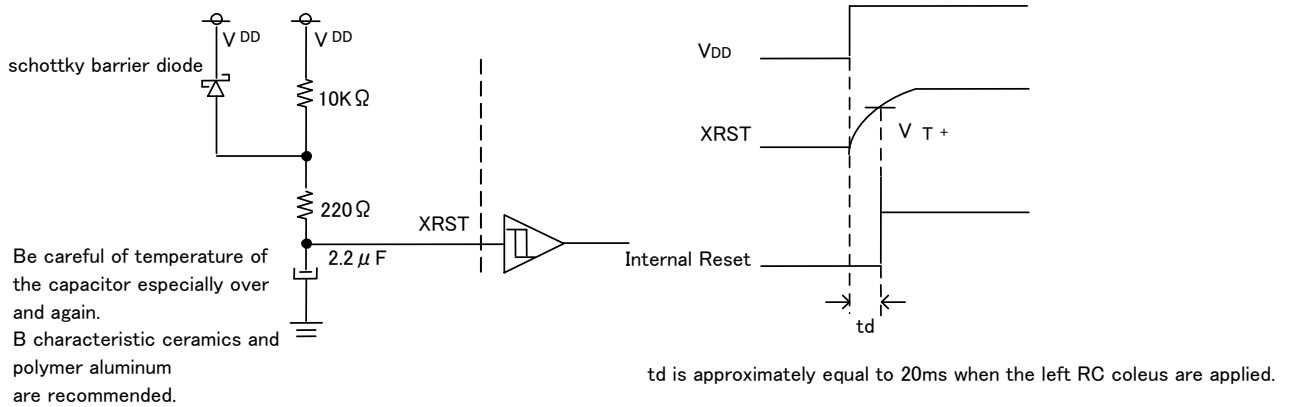


Figure-11 Power On Reset by external a CR circuit

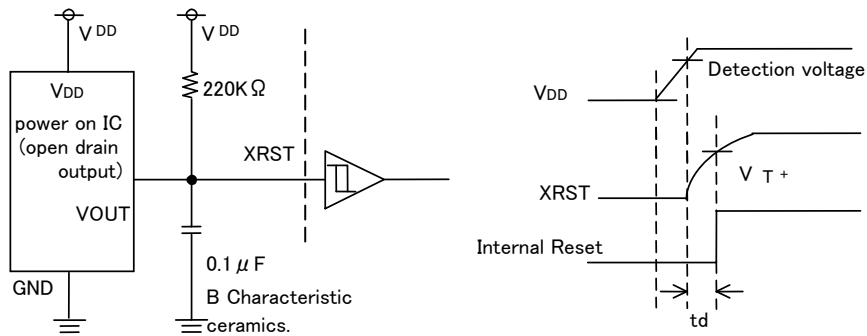


Figure-12 Power On Reset by specific IC

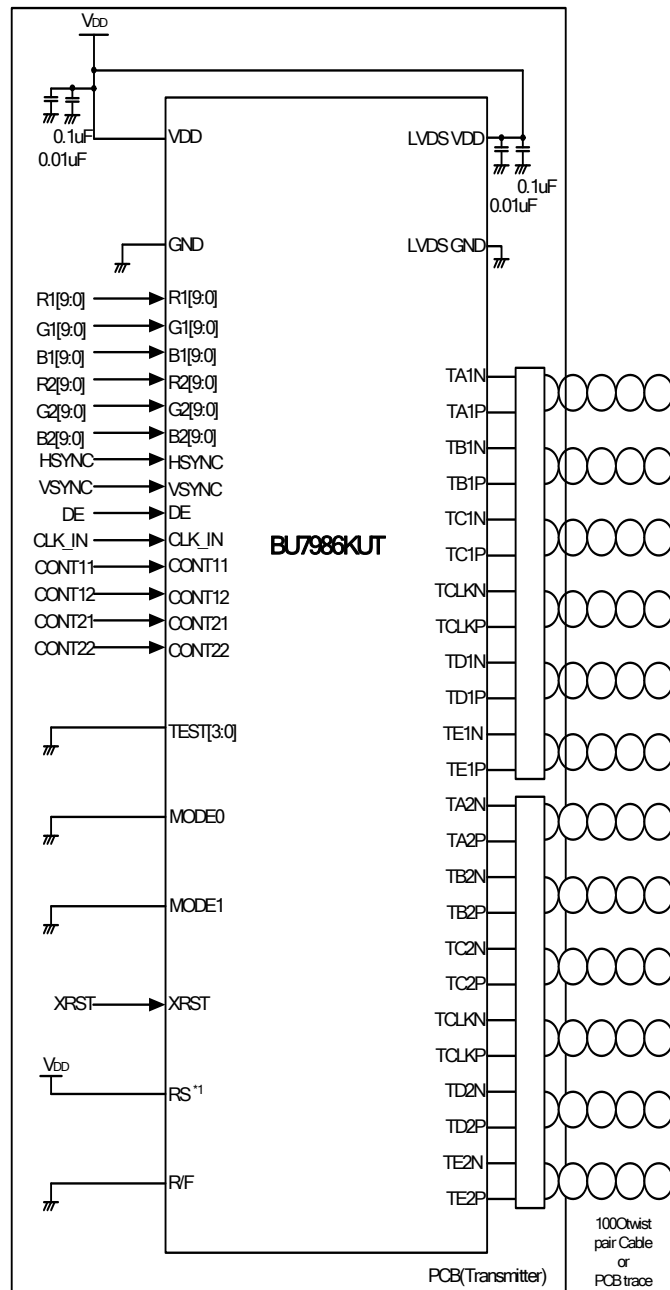
● 10bit LVCMOS Level Input

Example:

BU7986KUT : Falling edge

Normal swing

Dual-in / Dual-out mode



- *1 :
 If RS pin is tied to V_{DD} , LVDS swing is 350m V.
 If RS pin is tied to GND, LVDS swing is 200m V.

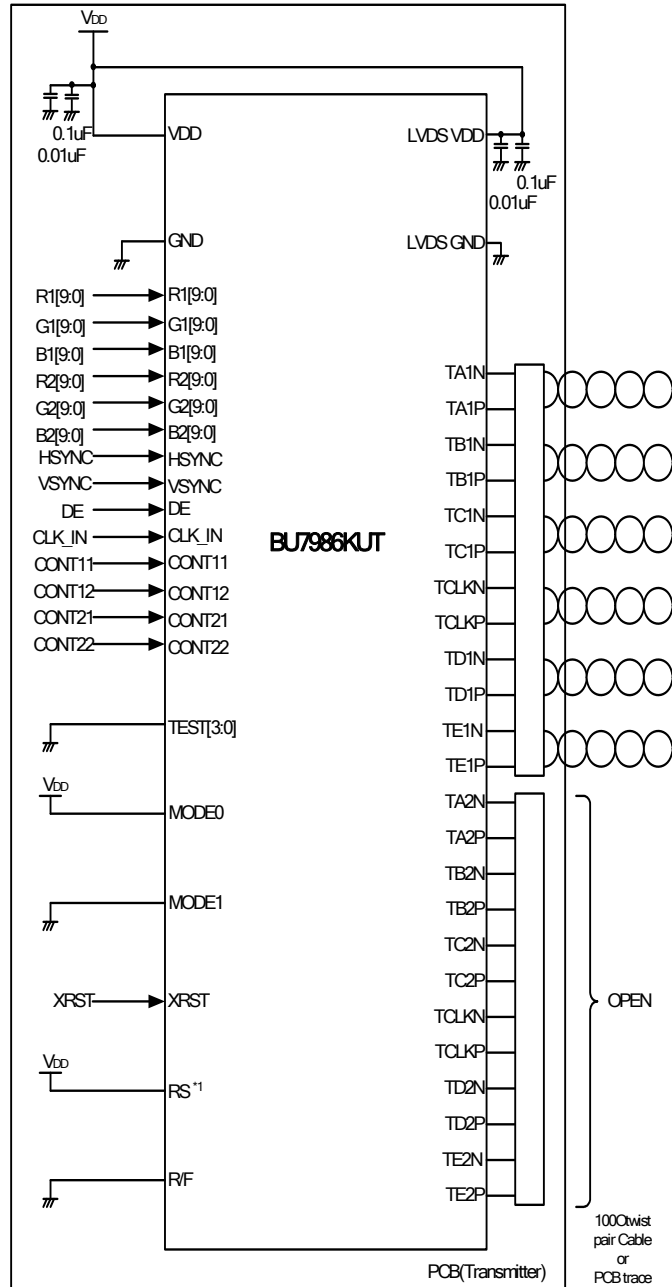
● 10bit LVCMOS Level Input

Example:

BU7986KUT : Falling edge

Normal swing

Dual-in / Single-out mode



- *1 :
 If RS pin is tied to V_{DD}, LVDS swing is 350m V.
 If RS pin is tied to GND, LVDS swing is 200m V.

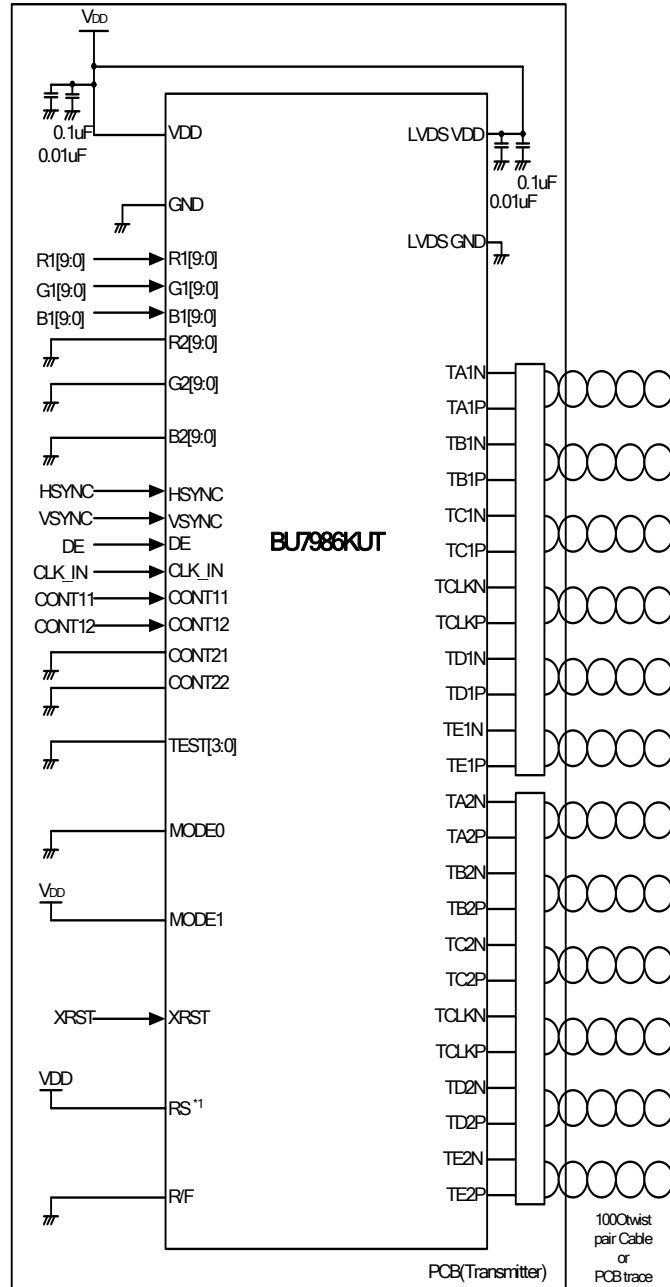
● 10bit LVCMOS Level Input

Example:

BU7986KUT : Falling edge

Normal swing

Single-in / Dual-out mode



- *1 : If RS pin is tied to V_{DD}, LVDS swing is 350m V.
 If RS pin is tied to GND, LVDS swing is 200m V.

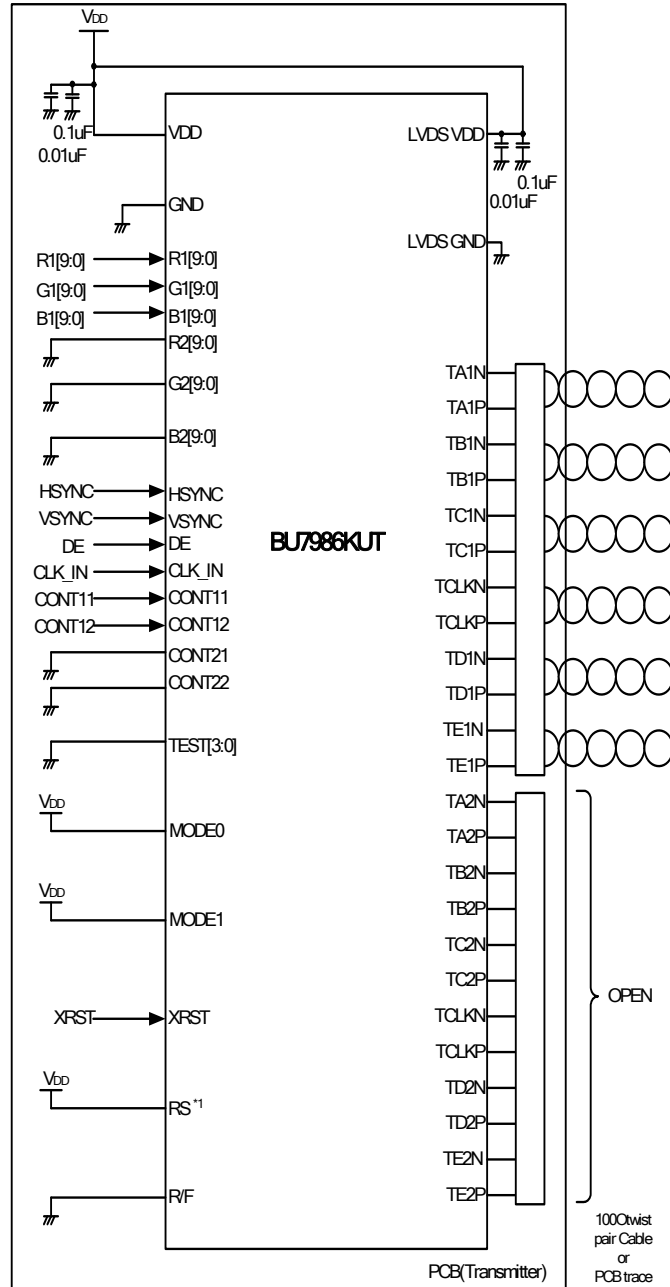
● 10bit LVCMOS Level Input

Example:

BU7986KUT : Falling edge

Normal swing

Single-in / Single-out mode



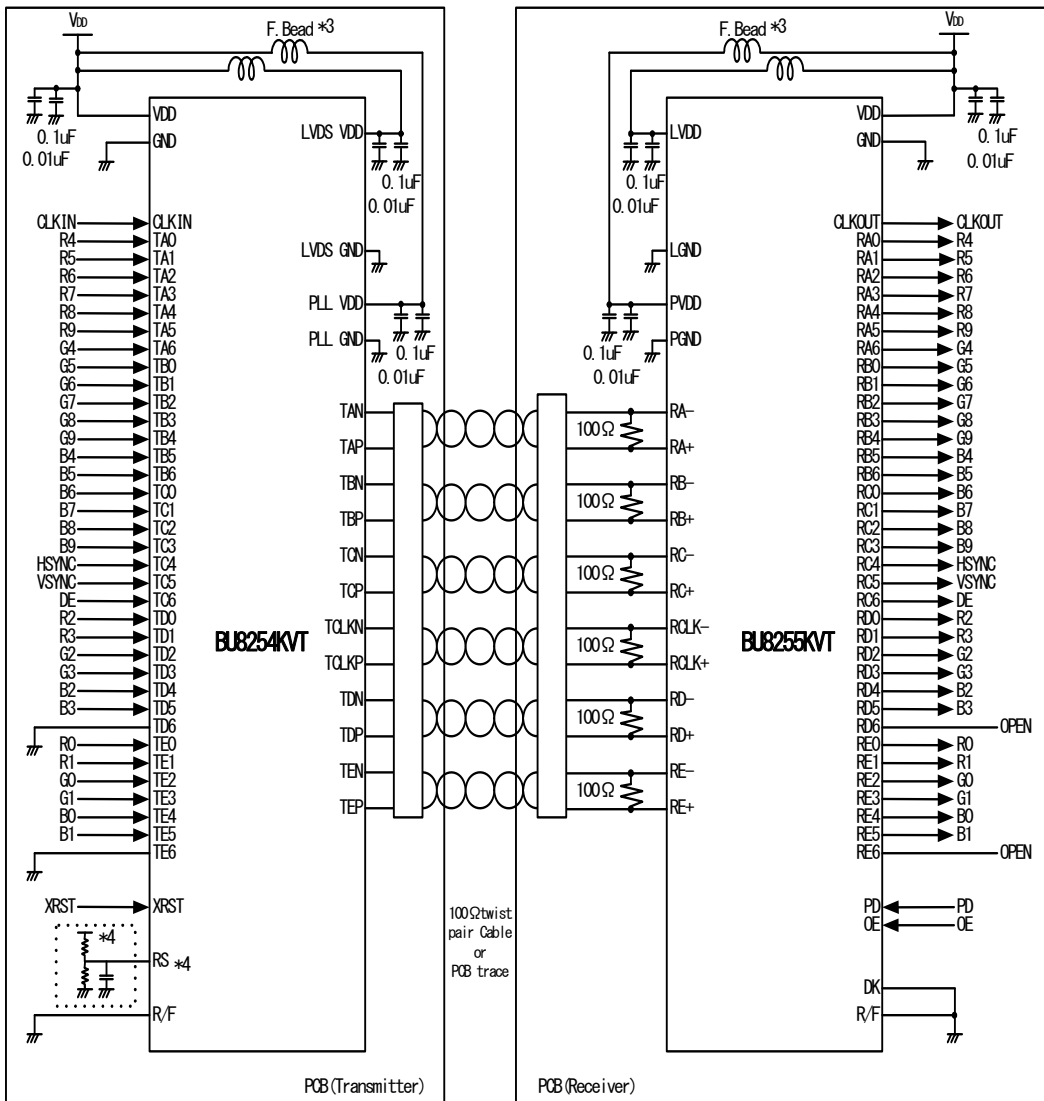
- *1 : If RS pin is tied to V_{DD}, LVDS swing is 350m V.
 If RS pin is tied to GND, LVDS swing is 200m V.

● 10bit Small Swing Input

Example:

BU8254KVT : LVCMOS level input/Falling edge/Normal swing

BU8255KVT : Falling edge

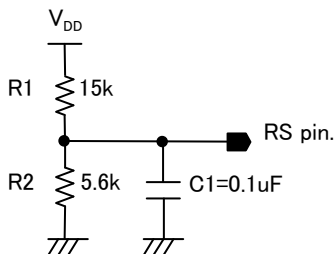


*3 : Recommended Parts:

F.Bead : BLM18A-Series (Murata Manufacturing)

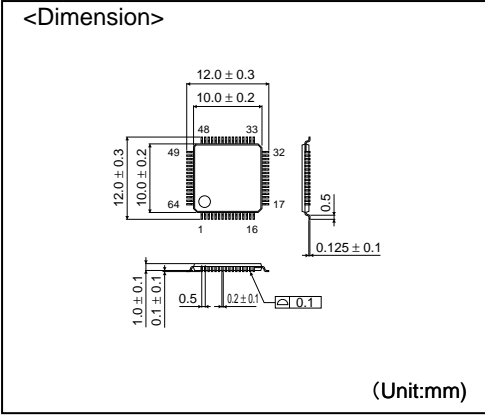
*4 : RS pin acts as VREF input pin when input voltage is set to half of high level signal input.

We recommend to locate by-pass condenser near the RS pin.



Example for LVCMOS(1.8V input):(R1,R2)=(15k Ω,5.6k Ω)

TQFP64V



<Packing information>

Container	Tray(with dry pack)
Quantity	1000pcs
Direction of feed	Direction of product is fixed in a tray.

※When you order , please order in times the amount of package quantity.

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Stuttgart	TEL: +49-711-72723710	FAX: +49-711-72723720	Huizhou	TEL: +86-752-205-1054	FAX: +86-752-205-1059
France	TEL: +33-1-5697-3060	FAX: +33-1-5697-3080	Xiamen	TEL: +86-592-238-5705	FAX: +86-592-239-8380
United Kingdom	TEL: +44-1-908-306700	FAX: +44-1-908-235788	Zhuhai	TEL: +86-756-3232-480	FAX: +86-756-3232-460
Denmark	TEL: +45-3694-4739	FAX: +45-3694-4789	Hong Kong	TEL: +852-2-740-6262	FAX: +852-2-375-8971
Barcelona	TEL: +34-9375-24320	FAX: +34-9375-24410	Taipei	TEL: +886-7-237-0881	FAX: +886-7-237-0881
Hungary	TEL: +36-1-4719338	FAX: +36-1-4719339	Kaohsiung	TEL: +886-7-237-0881	FAX: +886-7-238-7332
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